

MH190, Hall-Effect sensor, designed for electronic commutation of brush-less DC motor applications. The device includes an on-chip Hall voltage generator for magnetic sensing, a comparator that amplifies the Hall Voltage, and a Schmitt trigger to provide switching hysteresis for noise rejection, open collector output. An internal band gap regulator is used to provide temperature compensated supply voltage for internal circuits and allows a wide operating supply range. The device is identical except for magnetic switch points.

A south pole of sufficient strength will turn the output on. The North Pole is necessary to turn the output off. An on-board regulator permits operation with supply voltages of 4V to 30 V.

The package type is in a Halogen Free version was verified by third party organization.

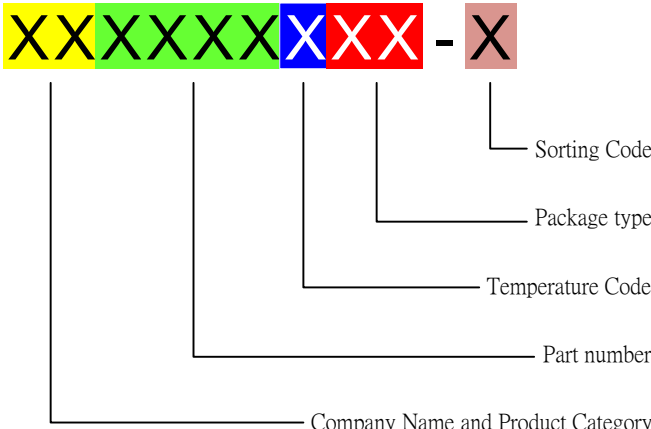
Features and Benefits

- Optimized for BLDC motor applications
- High Peak Voltage of 65V
- 100% tested at 125 °C for K.
- Temperature compensation function

Applications

- High temperature Fan motor
- 3 phase BLDC motor application
- Fan motor application
- Speed sensing
- Revolution counting
- E-Bike

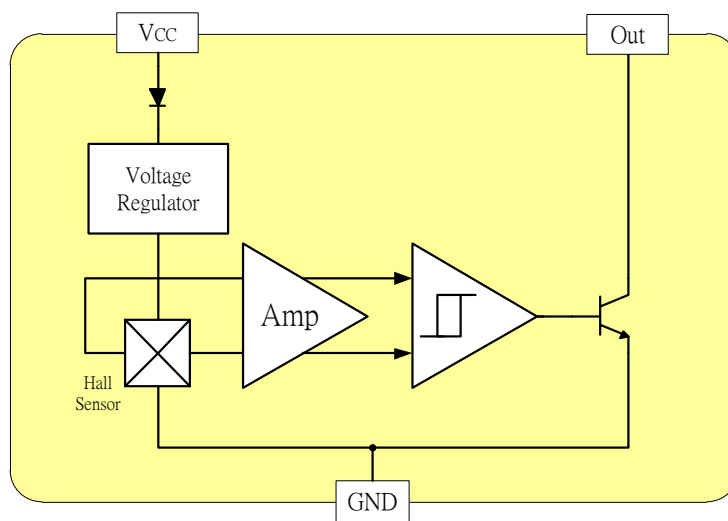
Ordering Information

	<p>Company Name and Product Category MH:MST Hall Effect/MP:MST Power MOSFET</p> <p>Part number 181,182,183,184,185,248,249,276,477,381,381F,381R,382..... If part # is just 3 digits, the fourth digit will be omitted.</p> <p>Temperature range E: 85 °C, I: 105 °C, K: 125 °C, L: 150 °C</p> <p>Package type UA:TO-92S,VK:TO-92S(4pin),VF:TO-92S(5pin),SO:SOT-23, SQ:QFN-3,ST:TSOT-23,SN:SOT-553,SF:SOT-89(5pin)</p> <p>Sorting α, β, Blank.....</p>
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Part No.	Temperature Suffix	Package Type
MH190KUA	K (-40°C to + 125°C)	UA (T0-92S)
MH190KSO	K (-40°C to + 125°C)	SO (SOT-23)
MH190EUA	E (-40°C to + 85°C)	UA (T0-92S)
MH190ESO	E (-40°C to + 85°C)	SO (SOT-23)

KUA spec is using in industrial and automotive application. Special Hot Testing is utilized.

Functional Diagram



Absolute Maximum Ratings At ($T_a=25^\circ\text{C}$)

Characteristics		Values	Unit
Supply voltage, (V_{cc})		65	V
Out voltage, (V_{out})		65	V
Reverse voltage, (V_{cc}) (V_{out})		-32	V
Magnetic flux density		Unlimited	Gauss
Output current, (I_{out})		25	mA
Operating Temperature Range, (T_a)	“E” version	-40 to +85	°C
	“K” version	-40 to +125	°C
Storage temperature range, (T_s)		-65 to +150	°C
Maximum Junction Temp, (T_j)		150	°C
Thermal Resistance	(θ_{ja}) UA / SO	206 / 543	°C/W
	(θ_{jc}) UA / SO	148 / 410	°C/W
Package Power Dissipation, (P_D) UA / SO		606 / 230	mW

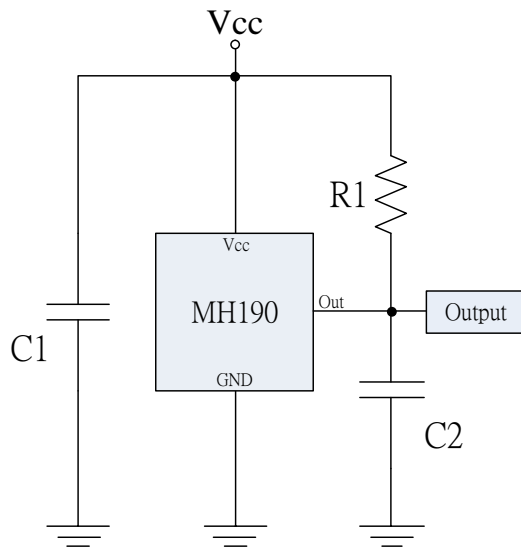
Note: Do not apply reverse voltage to V_{cc} and V_{out} Pin, It may be caused for Miss function or damaged device.

Electrical Specifications

DC Operating Parameters : $T_A = +25\text{ }^\circ\text{C}$, $V_{CC} = 12\text{V}$

Parameters	Test Conditions	Min	Typ	Max	Units
Supply Voltage, (V_{CC})	Operating	4.0		30.0	V
Supply Current, (I_{CC})	$B < B_{OP}$		3.0	8.0	mA
Output Saturation Voltage, (V_{sat})	$I_{OUT} = 5\text{ mA}$, $B > B_{OP}$			500.0	mV
Output Leakage Current, (I_{off})	I_{OFF} $B < B_{RP}$, $V_{OUT} = 24\text{V}$			10.0	μA
Output Rise Time, (T_R)	$R_L = 820\ \Omega$, $C_L = 20\text{pF}$		1.5		μS
Output Fall Time, (T_F)	$R_L = 820\ \Omega$; $C_L = 20\text{pF}$		1.5		μS
Operate Point, (B_{OP})		10		110	Gauss
Release Point, (B_{RP})		-110		-10	Gauss
Hysteresis, (B_{HYS})			100		Gauss

Typical application circuit

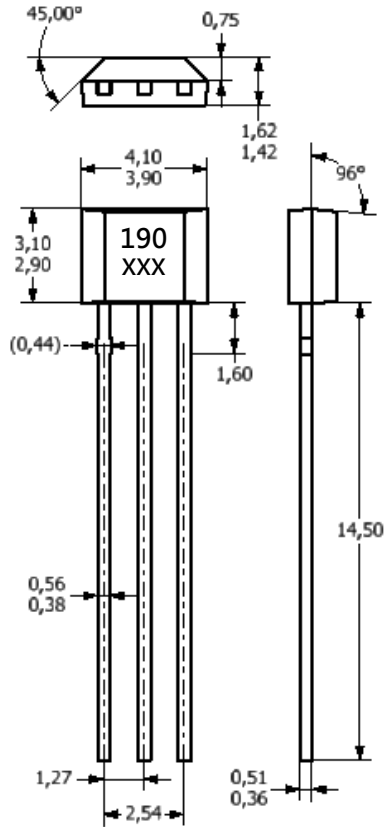


C1 : 1000PF
 C2 : 15PF
 R1 : 10K Ω

Sensor Location, Package Dimension and Marking

MH190 Package

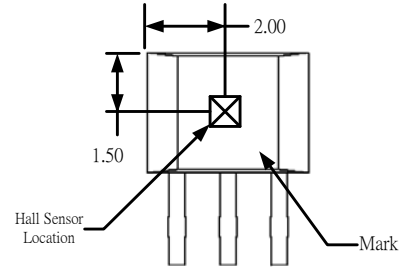
UA Package



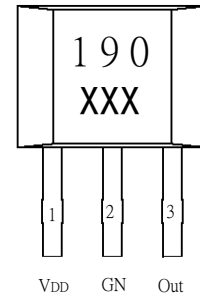
NOTES:

- 1).Controlling dimension: mm
 - 2).Leads must be free of flash and plating voids
 - 3).Do not bend leads within 1 mm of lead to package interface.
 - 4).PINOUT:
- | | |
|-------|--------|
| Pin 1 | Vcc |
| Pin 2 | GND |
| Pin 3 | Output |

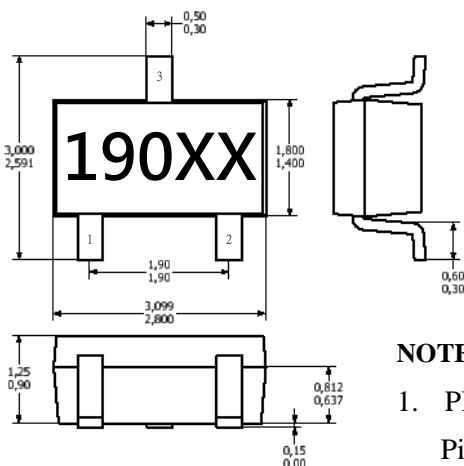
Hall Chip location



Output Pin Assignment (Top view)



Package (SOT-23) (Top View)



NOTES:

1. PINOUT (See Top View at left :)
- | | |
|-------|-----------------|
| Pin 1 | V _{CC} |
| Pin 2 | Output |
| Pin 3 | GND |
2. Controlling dimension: mm
 3. Lead thickness after solder plating will be 0.254mm maximum

Hall Plate Chip Location (Bottom view)

